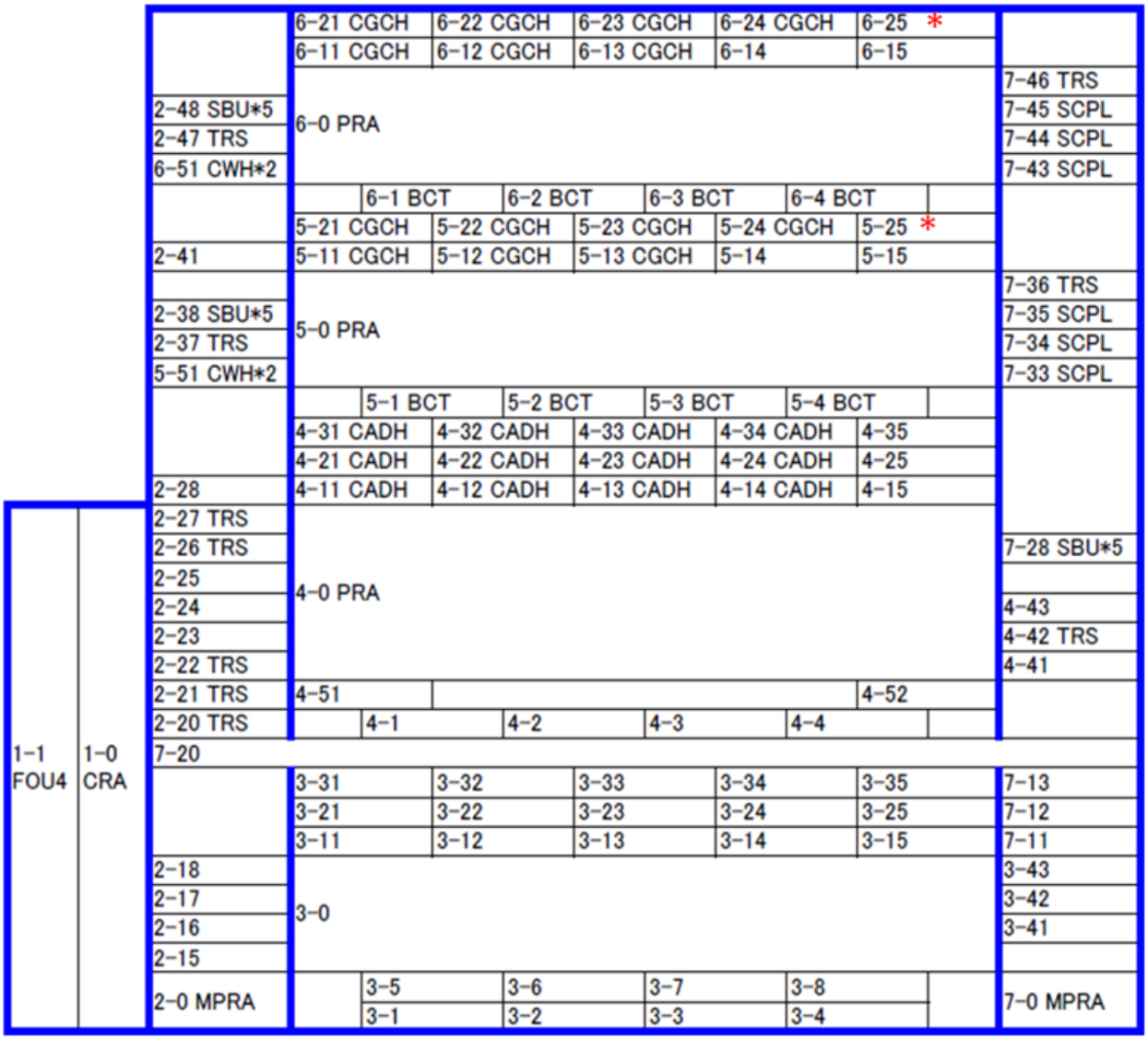
TEL Clean Track LITHIUS Pro-V BARC Track

- Manufacturer: Tokyo Electron
- Model: ProV 300mm Single Block Clean Track
- Wafer Size: 300mm
- General:
  - 4 Blocks: 1 Carrier, 2 Multi-purpose, 1 Process
  - 6 (250 WPH) Transfer Robot arms: 1 Carrier, 2 Multi-purpose, 3 Process
  - Stainless Exhaust Lines below Track
  - SECS1, SECS11, HMDS & GEM Interface required is iUSC
  - E87/GJG compliance
  - 2 Piece Wafer Block
  - Stack 1: No Process Modules – only HMDS Bubblers
  - Stack 2: No Process Modules – only HMDS Bubblers
  - Stack 3: 12 CADH modules (no spin modules)
  - Stack 4: 3 BCT Cups with 10 Nozzles
  - Stack 5: 3 BCT Cups with 10 Nozzles
  - AC Power Box with Noise filter: CE Mark Type
  - AC Power Box 208volts, 3-phase, star, 50/60Hz compatible, SCCR requirements
- Cassette Block (CSB)
  - (5) FOUP Loadports (with N2 purge Pre-plumbing)
  - Carrier RFID capability on CSB
  - CSB Pressure Sensor
- Main Block with 5 Process Stacks
  - Stack 1 & 2 No Process Modules or Robotic Arms
    - 12 HMDS Bubbler System
  - Stack 3 HMDS Processing Only
    - 1 Process Robotic Arm
  - Stack 4 BARC Processing
    - (4) BCT Modules with TCT style cups and backside rinse nozzles
    - (10) 1.2 mm Resist nozzles, (1) SRRC nozzle with Temp control per layer
    - (10) 0.8 mm Resist nozzles, (1) ARRC nozzle with Temp control per layer
    - (10) 3ml CRD resist dispense pumps
    - (10) 3ml ACRD resist dispense pumps
    - (10) Single Bottle Resist Supply Configuration
    - EBR angle adjustment capability
    - Bulk-FSI system for solvent dispense
    - Exhaust Pressure Control (EPC) per stack
    - Exhaust duct and drain case cleaning function
    - Exhaust Thermo Controller System in STHC
    - 4 Dispense Detection Systems (all COT modules)
    - Bevel Rinse nozzle (Ver 2)
    - IFF-S for RRC lines with ARRC-s
    - IFF-R (for Resist)
  - Stack 5 BARC Processing
    - (4) BCT Modules with TCT style cups and backside rinse nozzles
    - (10) 1.2 mm Resist nozzles, (1) SRRC nozzle with Temp control per layer
    - (10) 0.8 mm Resist nozzles, (1) ARRC nozzle with Temp control per layer
    - (10) 3ml CRD resist dispense pumps
    - (10) 3ml ACRD resist dispense pumps
    - (10) Single Bottle Resist Supply Configuration
    - EBR angle adjustment capability
    - Bulk-FSI system for solvent dispense
    - Exhaust Pressure Control (EPC) per stack
    - Exhaust duct and drain case cleaning function
    - Exhaust Thermo Controller System in STHC
    - 4 Dispense Detection Systems (all COT modules)

    - Bevel Rinse nozzle (Ver 2)
    - IFF-S for RRC lines with ARRC-s
    - IFF-R (for Resist)
- (12) Chilling Adhesion Processing Station (CADH)
    - Wafer Wedging function using Plate Temperature sensor SW calculation
    - (2) Bubbler Type HMDS Tank located in Main processing block
    - Gap Pin type UPIMOL proximity pins on chilling arm
- (6) Slim Chill Plate Process Station (SCPL)
    - Wafer wedging function using vacuum detection sensor
    - Gap Pin type UPIMOL proximity pins on chilling arm
- (2) Chilling High Precision Hot Plate Process Station (CHCH)
    - Heated Exhaust Chamber
    - Wafer Wedging function using Plate Temperature sensor SW
    - Gap Pin type ceramic proximity pins on chilling arm
- (14) General Purpose Hot Plate Process Station (CGCH)
    - Heated Exhaust Chamber
    - Wafer Wedging function using Plate Temperature sensor SW
    - Gap Pin type UPIMOL proximity pins on chilling arm
- (1) TEL System Temp and Humidity Controller (STHC)
    - (1) Shinwa unit for system environment control, chemical temperature control and CPL temperature control
    - (1) Return Air Box - Plenum
- (2) New Style Chemical Cabinets
    - (1) HMDS Canister (3 gallons with gauge)
    - (1) 3-Pump Solvent chemical supply system
    - (1) 2-Pump Developer chemical supply system
    - (1) Sub operation panel
    - Top side facility connection
    - CRF for solvent based PCS
- (1) New Style AC Power Box
    - Dual Feed facility supply power with 2 separate breakers
    - Top side facility connection
    - Ring type GND connection
- **SEE SYSTEM LAYOUT ON NEXT PAGE**


6-21 CGCH
6-22 CGCH
6-23 CGCH
6-24 CGCH
6-25 *
6-11 CGCH
6-12 CGCH
6-13 CGCH
6-14
6-15
7-46 TRS
2-48 SBU*5
7-45 SCPL
2-47 TRS
6-0 PRA
7-44 SCPL
6-51 CWH*2
7-43 SCPL
6-1 BCT
6-2 BCT
6-3 BCT
6-4 BCT
5-21 CGCH
5-22 CGCH
5-23 CGCH
5-24 CGCH
5-25 *
2-41
5-11 CGCH
5-12 CGCH
5-13 CGCH
5-14
5-15
7-36 TRS
2-38 SBU*5
7-35 SCPL
2-37 TRS
5-0 PRA
7-34 SCPL
5-51 CWH*2
7-33 SCPL
5-1 BCT
5-2 BCT
5-3 BCT
5-4 BCT
4-31 CADH
4-32 CADH
4-33 CADH
4-34 CADH
4-35
4-21 CADH
4-22 CADH
4-23 CADH
4-24 CADH
4-25
2-28
4-11 CADH
4-12 CADH
4-13 CADH
4-14 CADH
4-15
2-27 TRS
2-26 TRS
7-28 SBU*5
2-25
4-0 PRA
2-24
4-43
2-23
4-42 TRS
2-22 TRS
4-41
2-21 TRS
4-51
4-52
2-20 TRS
4-1
4-2
4-3
4-4
1-1 FOU4
1-0 CRA
7-20
3-31
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2-17
3-0
3-42
2-16
3-41
2-15
2-0 MPRA
3-5
3-6
3-7
3-8
7-0 MPRA
3-1
3-2
3-3
3-4